Product / Package Information

Package	SOIC_W
Body Size	300 mils
Lead Count	16
Terminal Finish	100Sn
MS Number	MS011040B

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.61 E-01	87.3	873000	57.96	579613
Thermosets	Phenol Resin	Proprietary	1.35 E-02	4.5	45000	2.99	29877
Thermosets	Epoxy Resin 1	Proprietary	8.98 E-03	3.0	30000	1.99	19918
Thermosets	Epoxy Resin 2	Proprietary	8.98 E-03	3.0	30000	1.99	19918
Others	Others	Proprietary	5.99 E-03	2.0	20000	1.33	13279
Other inorganic materials	Carbon Black	1333-86-4	5.99 E-04	0.2	2000	0.13	1328
Subtotal			2.99 E-01	100.0	1000000	66.39	663933

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.37 E-01	97.5	975000	30.29	302906
Copper & its alloys	Iron	7439-89-6	3.29 E-03	2.35	23500	0.73	7301
Copper & its alloys	Zinc	7440-66-6	1.68 E-04	0.12	1200	0.04	373
Copper & its alloys	Phosphorus	7723-14-0	4.20 E-05	0.03	300	0.01	93
Subtotal			1.40 E-01	100	1000000	31.07	310673

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.42 E-03	100	1000000	0.31	3138

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.04 E-03	100	1000000	1.12	11173

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.00 E-04	99.99	1000000	0.11	1108

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.99 E-03	100	1000000	0.88	8845

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.93 E-04	77.00	770000	0.09	871
Other organic materials	Acrylic resin	Proprietary	3.57 E-05	7.00	70000	0.01	79
Other organic materials	Acrylate	Proprietary	2.80 E-05	5.50	55000	0.006	62
Other organic materials	Polybutadiene derivative	Proprietary	2.29 E-05	4.5	45000	0.005	51
Other organic materials	Epoxy resin	Proprietary	1.27 E-05	2.5	25000	0.003	28
Other organic materials	Butadiene Copolymer	Proprietary	7.65 E-06	1.5	15000	0.002	17
Others	Additive	Proprietary	7.65 E-06	1.5	15000	0.002	17
Others	Peroxide	Proprietary	2.55 E-06	0.5	5000	0.001	6
Subtotal			5.10 E-04	100	1000000	0.11	1131

	Weight (g)	Percentage (%)	PPM
Package Totals	**4.51 E-01**	100	1000000

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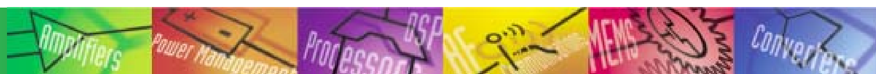

Product / Package Information

Package	SOIC_W
Body Size	300 mil
Lead Count	16
Terminal Finish	NiPdAu
MS Number	MS011574A

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.63 E-01	88.00	880000	58.43	584261
Thermosets	Epoxy & Phenol resin	Proprietary	3.44 E-02	11.50	115000	7.64	76352
Other inorganic materials	Carbon black	1333-86-4	1.50 E-03	0.50	5000	0.33	3320
Subtotal			2.99 E-01	100.00	1000000	66.39	663933

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.37 E-01	97.57	975706	30.31	303125
Copper & its alloys	Iron	7439-89-6	3.19 E-03	2.28	22789	0.71	7080
Copper & its alloys	Zinc	7440-66-6	1.77 E-04	0.13	1263	0.04	392
Copper & its alloys	Phosphorus	7723-14-0	3.40 E-05	0.02	242	0.01	75
Subtotal			1.40 E-01	100.00	1000000	31.07	310673

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	6.28 E-03	97.27	972697	1.39	13920
Precious metals	Palladium	7440-05-3	1.46 E-04	2.26	22621	0.03	324
Precious metals	Gold	7440-57-5	3.02 E-05	0.47	4683	0.007	67
Subtotal			6.45 E-03	100.00	1000000	1.43	14311

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.00 E-04	99.99	1000000	0.11	1108

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.99 E-03	100.00	1000000	0.88	8845

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.93 E-04	77.00	770000	0.09	871
Other organic materials	Acrylic resin	Proprietary	3.57 E-05	7.00	70000	0.01	79
Other organic materials	Acrylate	Proprietary	2.80 E-05	5.50	55000	0.01	62
Other organic materials	Polybutadiene derivative	Proprietary	2.29 E-05	4.50	45000	0.01	51
Other organic materials	Epoxy resin	Proprietary	1.27 E-05	2.50	25000	0.00	28
Other organic materials	Butadiene Copolymer	Proprietary	7.65 E-06	1.50	15000	0.00	17
Others	Additive	Proprietary	7.65 E-06	1.50	15000	0.00	17
Others	Peroxide	Proprietary	2.55 E-06	0.50	5000	0.00	6
Subtotal			5.10 E-04	100.00	1000000	0.11	1131

	Weight (g)	Percentage (%)	PPM
Package Totals	**4.51 E-01**	**100.00**	**1000000**

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Product / Package Information

Package	SOIC_W
Body Size	300 mils
Lead Count	16
Terminal Finish	SnPb
MS Number	MS011562A

Environmental Compliance Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.63 E-01	87.7	877000	58.23	582269
Thermosets	Epoxy Resin	Proprietary	1.50 E-02	5.0	50000	3.32	33197
Thermosets	Phenol Resin	Proprietary	1.50 E-02	5.0	50000	3.32	33197
Thermosets	Epoxy Cresol Novolac	29690-82-2	5.99 E-03	2.0	20000	1.33	13279
Other inorganic materials	Carbon Black	1333-86-3	8.98 E-04	0.3	3000	0.20	1992
Subtotal			2.99 E-01	100	1000000	66.39	663933

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.37 E-01	97.5	975000	30.29	302906
Copper & its alloys	Iron	7439-89-6	3.29 E-03	2.35	23500	0.73	7301
Copper & its alloys	Zinc	7440-66-6	1.68 E-04	0.12	1200	0.04	373
Copper & its alloys	Phosphorus	7723-14-0	4.20 E-05	0.03	300	0.01	93
Subtotal			1.40 E-01	100.00	1000000	31.07	310673

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.42 E-03	100.0	1000000	0.31	3138

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	4.28 E-03	85.0	850000	0.95	9497
Tin & its alloys	Lead	7439-92-1	7.56 E-04	15.0	150000	0.17	1676
Subtotal			5.04 E-03	100.0	1000000	1.12	11173

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.00 E-04	99.99	1000000	0.11	1108

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.99 E-03	100.0	1000000	0.88	8845

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.08 E-04	80	800000	0.09	904
Thermosets	Epoxy Resin	Proprietary	7.65 E-05	15	150000	0.02	170
Others	Curing agent & hardener	Proprietary	2.55 E-05	5	50000	0.01	57
Subtotal			5.10 E-04	100	1000000	0.11	1131

	Weight (g)	Percentage (%)	PPM
Package Totals	**4.51 E-01**	**100.00**	**1000000**

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